BigTwin SuperServer SYS-222BT-HNR

2U 4-Node BigTwin with 6 hot-swap 2.5" NVMe drives per node

Key Applications

All-Flash NVMe Hyperconverged Infrastructure, Container-as-a-Service;
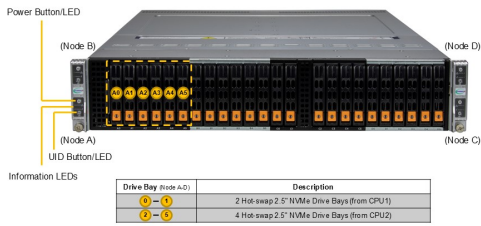Application Accelerator, High-Performance File System, Diskless HPC Clusters,

Key Features

- Four hot-pluggable systems (nodes) in a 2U form factor. Each node supports the following:;
- Dual Socket E2 (LGA-4710) Intel® Xeon® 6700/6500 series processors with P-cores or 6700 series processors with E-cores up to 205W with air cooling or 350W with liquid cooling;
- Up to 16 DIMMs supporting up to 4TB DDR5-6400 in 1DPC;
- Flexible networking with up to 1 OCP 3.0 compatible AIOM slots;
- Up to 2 PCIe 5.0 x16 LP + 1 PCIe 5.0 x16 AIOM slots;
- Up to 6 front hot-swap 2.5" NVMe drive bays;
- 2 Redundant 3600W Titanium Level power supplies;
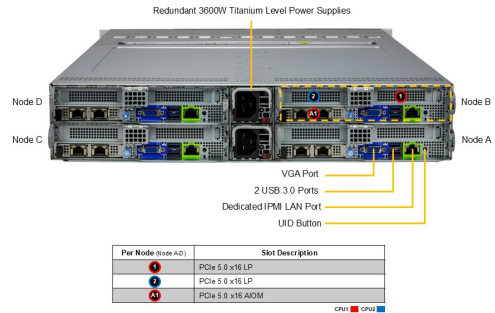- 2U Rackmount chassis with 28.75" (730mm) depth;

Form Factor	2U Rackmount Enclosure: 449 x 88 x 730mm (17.68" x 3.47" x 28.75") Package: 626 x 248 x 1150mm (24.65" x 9.76" x 45.28")
Processor	Dual Socket E2 (LGA-4710) Intel® Xeon® 6700/6500 series processors with P-cores or 6700 series processors with E-cores P-cores: Up to 86C/172T; Up to 336MB Cache per CPU E-cores: Up to 144C/144T; Up to 108MB Cache per CPU
System Memory	Slot Count: 16 DIMM slots Max Memory (1DPC): Up to 4TB 6400MT/s ECC DDR5 RDIMM
Drive Bays Configuration	Default: Total 6 bays • 6 front hot-swap 2.5" PCIe 5.0 NVMe drive bays Option A: Total 2 bays • 2 front hot-swap 2.5" PCIe 5.0 NVMe drive bays M.2: 2 M.2 PCIe 5.0 x4 NVMe slots (M-key 22110(default); VROC required for RAID)
Expansion Slots	Default • 2 PCIe 5.0 x16 LP slots • 1 PCIe 5.0 x16 AIOM slot (OCP 3.0 compatible)
On-Board Devices	Chipset: System on Chip Network Connectivity: Via AIOM
Input / Output	LAN: 1 RJ45 1 GbE Dedicated BMC LAN port USB: 2 USB 3.0 Gen2 Type-A ports(Rear) Video: 1 VGA port

(Front View – System)

(Rear View – System)

Power Button/LED
(Node B)
(Node D)
(Node A)
UID Button/LED
Information LEDs

Drive Bay (Node A-D)	Description
0 — 1	2 Hot-swap 2.5" NVMe Drive Bays (from CPU1)
2 — 5	4 Hot-swap 2.5" NVMe Drive Bays (from CPU2)

Redundant 3600W Titanium Level Power Supplies
Node D
Node C
Node B
Node A
VGA Port
2 USB 3.0 Ports
Dedicated IPMI LAN Port
UID Button

Per Node (Node A-D)	Slot Description
1	PCIe 5.0 x16 LP
2	PCIe 5.0 x16 LP
A1	PCIe 5.0 x16 AIOM

CPU1 ■ CPU2 ■

System Cooling	Fans: 4x 16K RPM Counter Rotating 80x80x56mm Fan(s)
	Air Shroud: 4 Air Shrouds
	Liquid Cooling: Direct to Chip (D2C) Cold Plate

Power Supply	2x 3600W Redundant (1 + 1) Titanium Level (96%) power supplies

System BIOS	BIOS Type: AMI 32MB Flash ROM

Management	SuperCloud Composer®; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); Supermicro Thin-Agent Service (TAS); SuperServer Automation Assistant (SAA) New!

PC Health Monitoring	FAN: Fans with tachometer monitoring
	Status monitor for speed control
	Pulse Width Modulated (PWM) fan connectors
	Temperature: Monitoring for CPU and chassis environment
	CPU: Monitors for CPU Cores, Chipset Voltages, Memory.
	8+4 Phase-switching voltage regulator

Dimensions and Weight	Weight: Gross Weight: 96.6 lbs (43.8 kg)
	Net Weight: 66.1 lbs (30 kg)
	Available Color: Black front & silver body

Operating Environment	RoHS Compliant
	Operating Temperature: 10°C to 35°C (50°F to 95°F)
	Non-operating Temperature: -30°C to 60°C (-22°F to 140°F)
	Operating Relative Humidity: 8% to 80% (non-condensing)
	Non-operating Relative Humidity: 8% to 90% (non-condensing)

Motherboard	**Super X14DBT-B**

Chassis	**CSE-217BQ2-R3K60P**